ASOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATIONAL AND ADDRESS INTO A DRIVENT AND A DRIVENT	C. Bannockl	burn, Illinois, A	ll rights reserved untions.	under both	This docum level parts, t	ent is a declara	tion of the s encompass	substances es all lowe	within the er level mat	manufacture terials for wh	er listed ite nich the ma	m. Note: nufacture	if the item is an as r has engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Dist				*	 * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi 					als and Mfg Information			
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
onsemi	mi										2024-05-03			
Contact Name	t Name Title - Contact					Phone - Contact*					Email - Contact*			
Product-Env-Stewards Product Envi			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representati			entative I			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Dat	e Version	1	Manufacturing Site		W	'eight*	UOM	Unit Type
	NVMTS TXG			PFN8*8 expansion		2024-05-03		:	РВВ		3	9.28	mg	Each
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Mat	ng / Grid Array Material Terminal Base Allo		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperatu		re Max Time at Peak Tempera		Temperatu	re Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30		second	s 3		
Comments														
evel 1 - maximum time at peak temperatu	e during so	ldering is 10-3	0 seconds											
For more information regarding material of	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	86.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.1033	mg
			Supplier	Iron (Fe)	7439-89-6		2.0234	mg
			Supplier	Copper (Cu)	7440-50-8		83.9475	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0258	mg
Die	6.27	mg	Supplier	Silicon (Si)	7440-21-3		6.27	mg
Die Attach Solder	15.3	mg	Supplier	Silver (Ag)	7440-22-4		0.3825	mg
			А	Lead (Pb)	7439-92-1	7a	14.1525	mg
			Supplier	Tin (Sn)	7440-31-5		0.765	mg
Lead Frame	103.2	mg	Supplier	Silver (Ag)	7440-22-4		0.0826	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1238	mg
			Supplier	Iron (Fe)	7439-89-6		2.4252	mg
			Supplier	Copper (Cu)	7440-50-8		100.5374	mg
			Supplier	Phosphorus (P)	7723-14-0		0.031	mg
Mold Compound-Black	103.88	mg		Epoxy resin	proprietary data		5.194	mg
			Supplier	Phenolic Resin	Proprietary Data		2.3892	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4155	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		2.3892	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		88.298	mg
Plating	4.48	mg	Supplier	Tin (Sn)	7440-31-5		4.48	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg